





High Megawatt Fuel Cell Power Converter Technology Impacts Study

(NIST/DOE Interagency Agreement)

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The Semiconductor Electronics Division

I. Introduction

II. Analysis of new technology impacts

III. PCS approaches being considered

- A. Low Voltage Inverters
- **B. Medium Voltage Inverters**
- **C. High Power Architectures**
- **IV. Inputs from High-MW community**

I. Introduction

Objective: Perform Independent Analysis (non commercial bias) of technologies that may reduce cost of Power Conditioning System (PCS) for future Fuel Cell Power Plants

Motivation:

- DoE SECA cost goals:
 - FC generator plant \$400/kw
 - including \$40-100/kW for power converter
- Today's FCE cost:
 - FC generator plant \$3,000/kW
 - including \$260/kW for power converter (to 18 kVAC)

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II. Analysis of Technology Impacts

- Methodology for impact study:
 - Classify power converter architectures and component technologies that may reduce cost
 - Perform tabular calculations of cost for each option using estimated advantages of new technologies
 - Use component modeling, and circuit and system simulations to verify and refine calculations
- Consider power electronics and/or transformer up to 18kVAC, and assume transformer from 18 kVAC to transmission level voltage

Analysis of Technology Impacts (cont.)

- Boundary conditions and performance parameters:
 - FC Stack: center tap ~700 VDC, 1000 A
 - Individual FC stack current control (may be necessary for FC reliability)
 - Fault tolerant and serviceable
- Converter cost components:
 - Semiconductors
 - Module Packaging
 - Cooling System
 - Magnetics: Filter Inductors and

HF voltage isolation transformers

- Transformer up to 18kV
- Breakers

- I. Introduction
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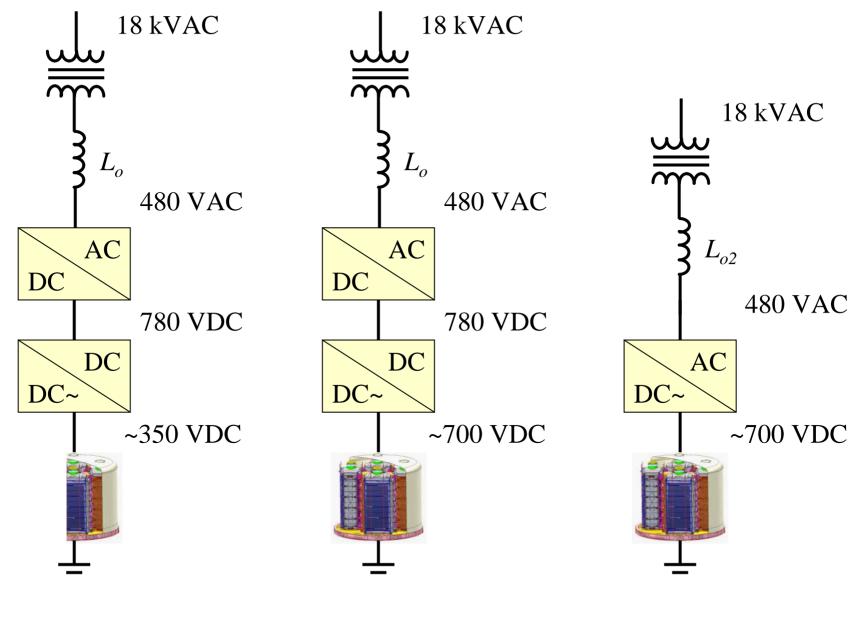
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IIIA. Low-Voltage Inverters

(Inverter to 480 VAC, then transformer to 18 kVAC)

- 1) First Generation: ~350 VDC FC, two stage DCDC/inverter: 750 VDC, 480 VAC
- 2) Baseline: Center-tap ~700 VDC FC, two stage regulator/inverter: 750VDC, 480 VAC
 - 1200 V is "Sweet spot" is silicon semiconductors
- 3) Present Generation: ~700 VDC FC, single stage inverter: 480 VAC
 - Fewer semiconductors because single stage
 - Larger filter inductor due to unregulated DC (filter sized for max VDC)
 - LV-DC Common Bus would stress FCs



1) First Generation

2) Baseline

3) Present Generation

Low-Voltage Semiconductors

- **Baseline:** 1200 V silicon IGBT switch and silicon PiN diode
 - 1200 V is sweet spot for silicon IGBTs at 15 20 kHz switching
- 1200 V silicon IGBT switch and SiC Schottky diode
 - More efficient at 20 kHz \rightarrow less heat removal cost
 - \rightarrow lower temperature and longer life
 - Less EMI \rightarrow less filter inductor cost
 - What is cost break point or 1200 V SiC Schottky?
- 1200 V SiC MOSFET Switch and SiC Schottky diode
 - Higher Frequency for DCDC but not necessary for inverter
 - What is cost break point for 1200 V SiC MOSFET Switch?

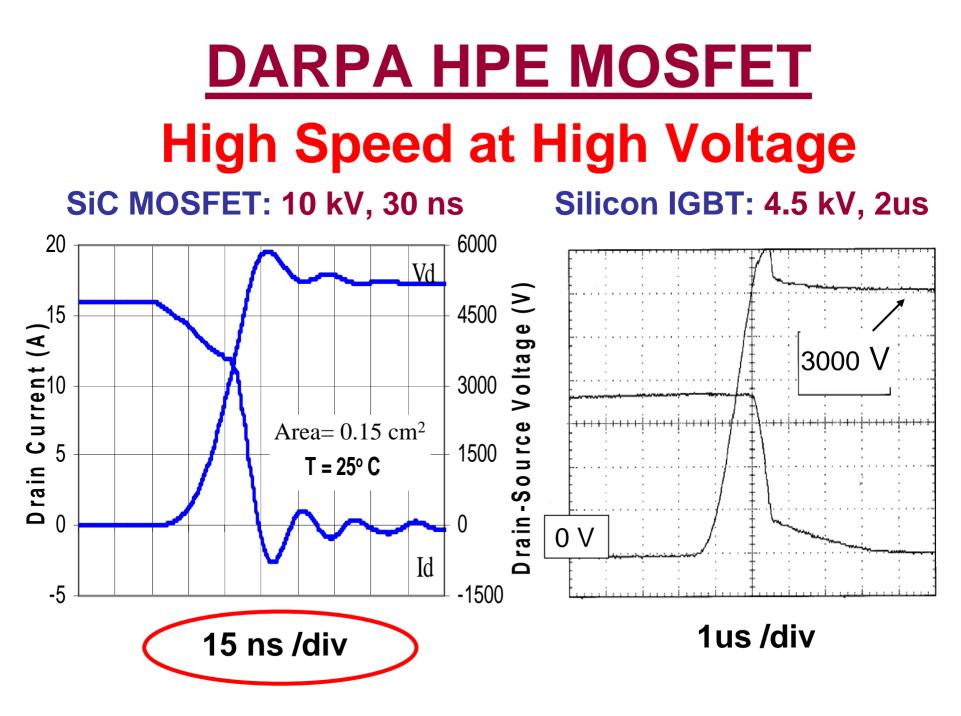
IIIB. Medium-Voltage Inverters

(Inverter to 4160 VAC, then transformer to 18 kVAC)

- Low voltage inverters require:
 - high current (1000 A) for 0.6 MW FC
 - high part count for 300 MW Power Plant (500 Inverters!!!)
- Medium Voltage Inverter: DCDC converter(s) to 6 kVDC, 4160 VAC inverter, transformer to 18 kVAC
 - Lower current semiconductor for inverter (140 A) for 0.6 MW FC
 - Multiple FCs for one high power inverter

High-Voltage Semiconductors

- **Baseline:** High Voltage Silicon Semiconductors (IGBT, IGCT)
 - Typically ~6 kV blocking voltage maximum
 - Require multi-level inverter for 4160 VAC (more semiconductors)
 - Low switching frequency (2 kHz) requires larger filter
- High-Voltage, High Frequency SiC Switch and Diodes
 - 10 kV, 20 kHz MOSFET switch and Schottky diode
 - Less filter inductor requirements due to high frequency
 - Fewer Semiconductors due to fewer levels
 - What is cost break point for HV-SiC Power Semicoductors?



IIIC. High Power Architectures

(8 X ~700 VDC FC to 4160 VAC)

- Individual LV-to-MV DCDC converters, Common MV inverter 8 X 0.6 MW DCDC converter form ~700 V to 6 kVDC, MVDC Common Bus,
 - 1 X 4.8 MW inverter to 4160 VAC
 - Reduces number of MV inverters but MV inverter current to 1000 A
 - Requires high voltage gain DC-DC converter
- 2) Series voltage-isolated LV-DC regulators, Common MV inverter
 8 X 0.6 MW voltage-isolated 750 VDC provides 6 kVDC,
 1 X 4.8 MW inverter to 4160 VAC
 - Reduces number of MV inverters but MV inverter current to 1000 A
 - Requires high-voltage isolation for 750 VDC regulator

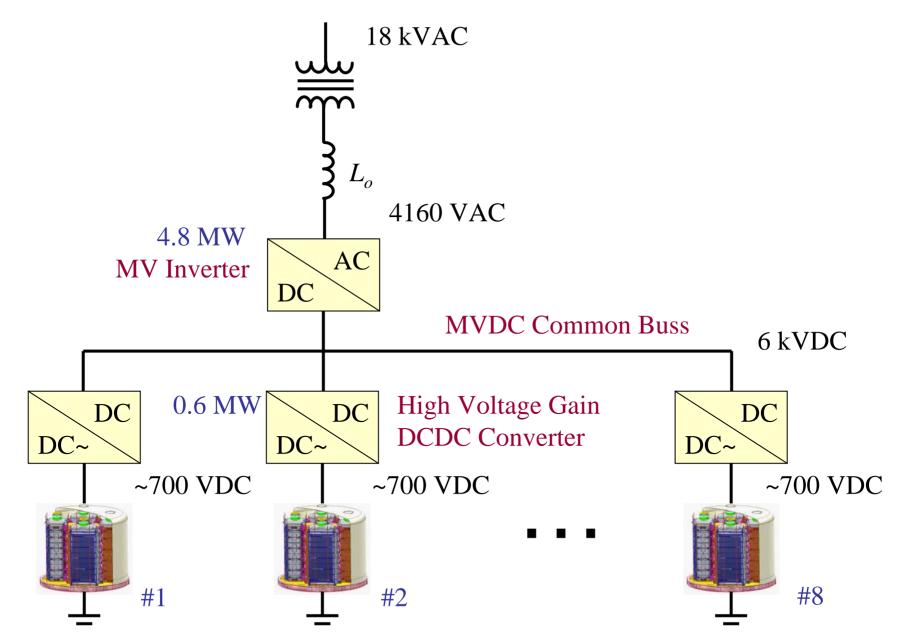
High Power Architectures (Continued)

(8 X ~700 VDC FC to 4160 VAC)

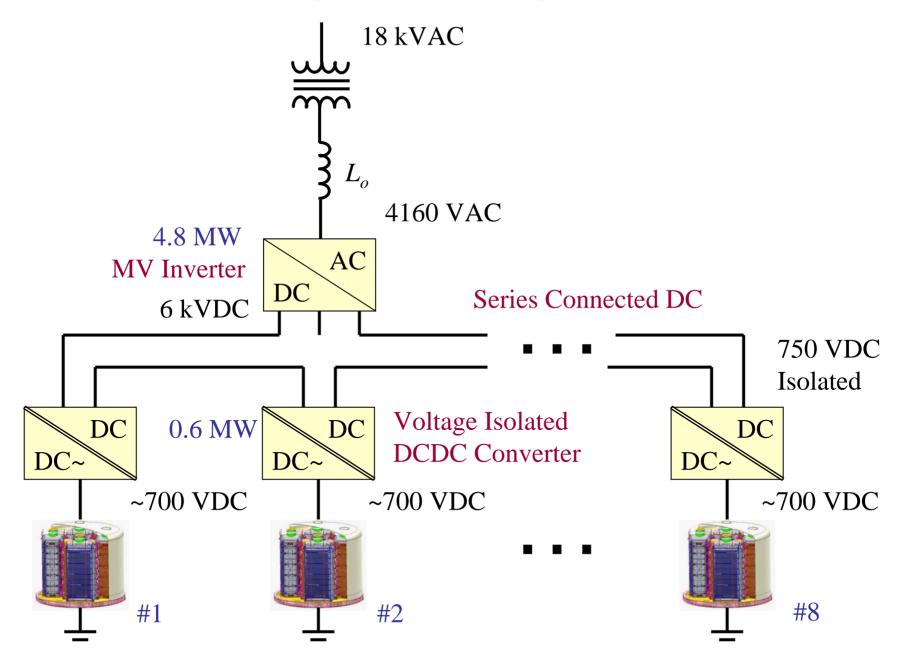
3) Cascade: Series-connected voltage-isolated LV-DC regulators, with low frequency phase-interleaved inverters
 8 X 0.6 MW voltage-isolated 750 VDC regulators series 8 X 750 V, 2.5 kHz phase interleaved inverters

- Uses 1200 V, 1000 A semiconductors to produce 4160 VAC
- 2.5 kHz switching provides effective 20 kHz
- improves tradeoff between switching loss and filter size
- Requires high-frequency, high-voltage isolation for 750 VDC regulator

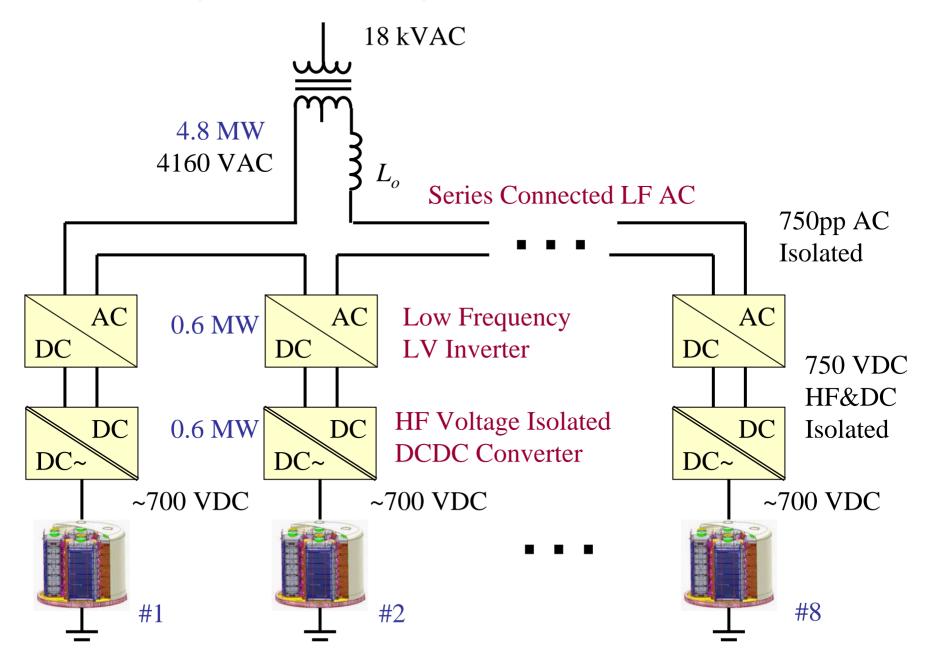
1) Individual LV-to-MV DCDC converters, Common MV inverter



2) Series connected, voltage-isolated LV-DC regulators, Common MV inverter



3) Cascade: voltage-isolated LV-DC regulators with phased interleaved LV inverters



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Needed: Inputs from High MW Community

- Preferred High-Megawatt architectures and topologies
- Specifications for filter requirements
 - Harmonics for power generation connectivity (e.g. IEEE1547)
 - EMI requirements
- Other advanced component technologies
 - Nano-crystalline magnetic materials for high-gain and voltage isolated converters
 - Packaging and advance cooling systems
 - Interconnects and modularity
 - Capacitors (Dry Q cap: low cost, low maintenance)